

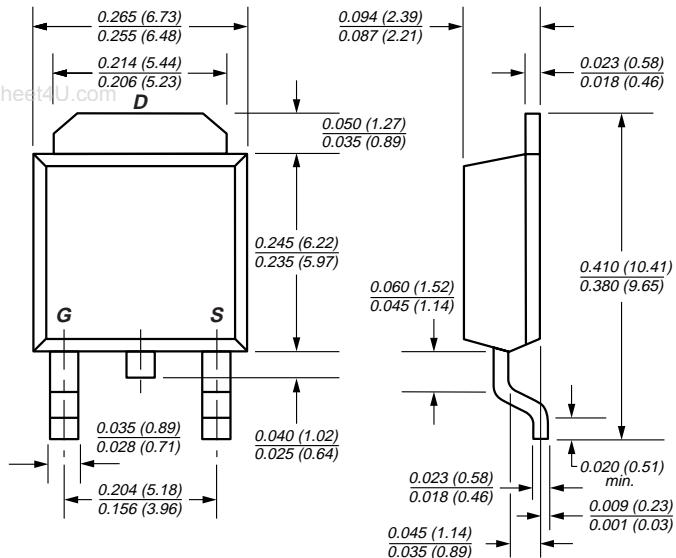


TRENCH
GENFET®

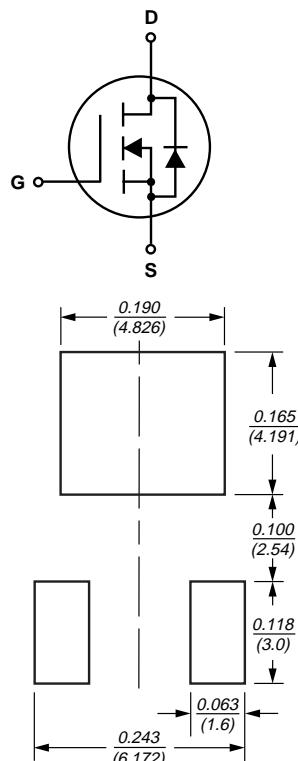
N-Channel Enhancement-Mode MOSFET

V_{DS} 30V R_{DS(ON)} 7mΩ I_D 78A

TO-252 (DPAK)



New Product



Mounting Pad Layout

Mechanical Data

Case: JEDEC TO-252 molded plastic body

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

High temperature soldering guaranteed:

250°C/10 seconds at terminals

Weight: 0.011oz., 0.4g

Features

- Advanced Trench Process Technology
- High Density Cell Design for Ultra Low On-Resistance
- Specially Designed for Low Voltage DC/DC Converters
- Fast Switching for High Efficiency

Maximum Ratings and Thermal Characteristics (T_C = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current ⁽¹⁾	I _D	78	A
Pulsed Drain Current	I _{DM}	180	
Maximum Power Dissipation	P _D	70 45	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Junction-to-Case Thermal Resistance	R _{θJC}	1.8	°C/W
Junction-to-Ambient Thermal Resistance ⁽²⁾	R _{θJA}	40	°C/W

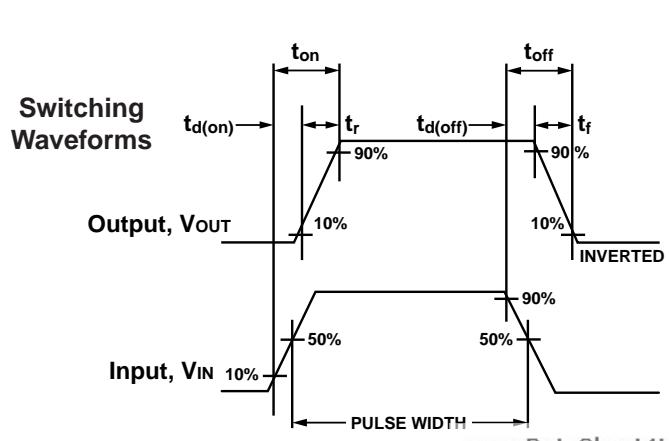
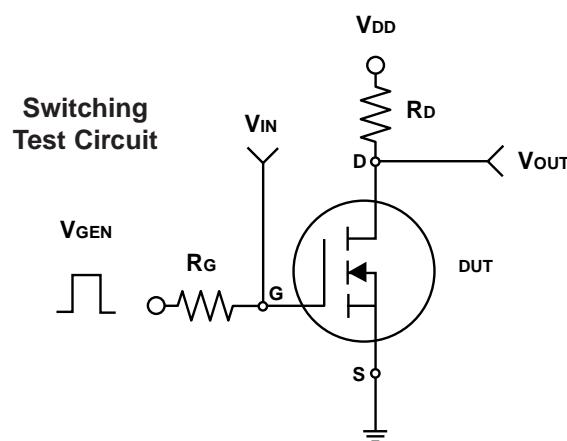
Notes: (1) Maximum DC current limited by the package

(2) 1-in² 2oz. Cu PCB mounted

N-Channel Enhancement-Mode MOSFET
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

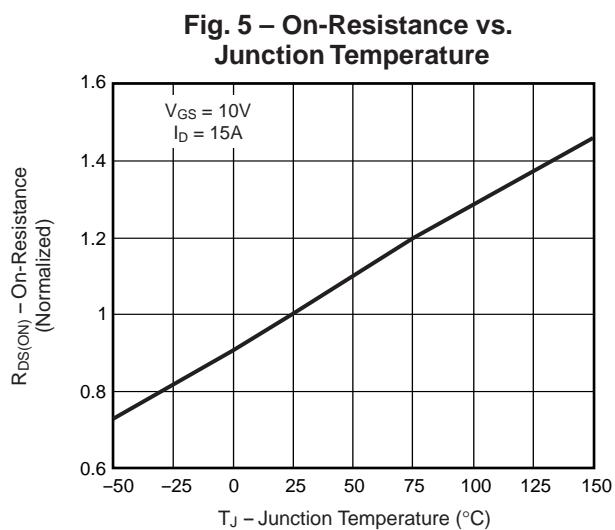
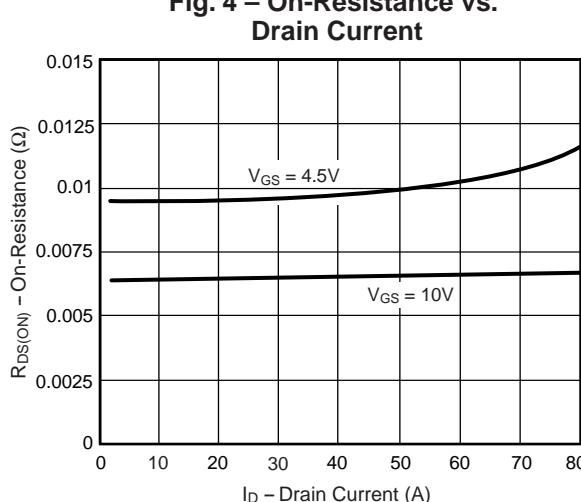
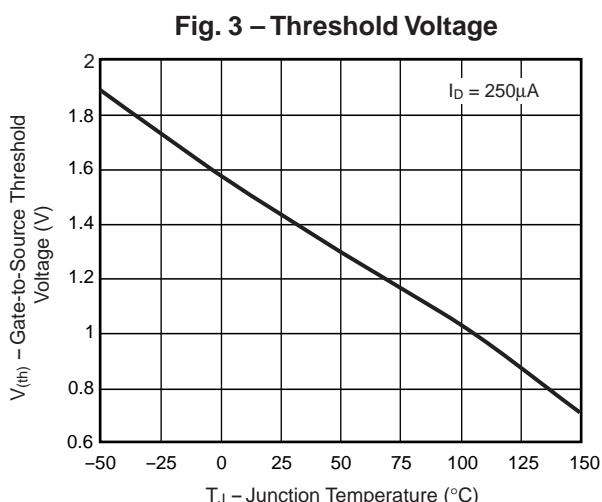
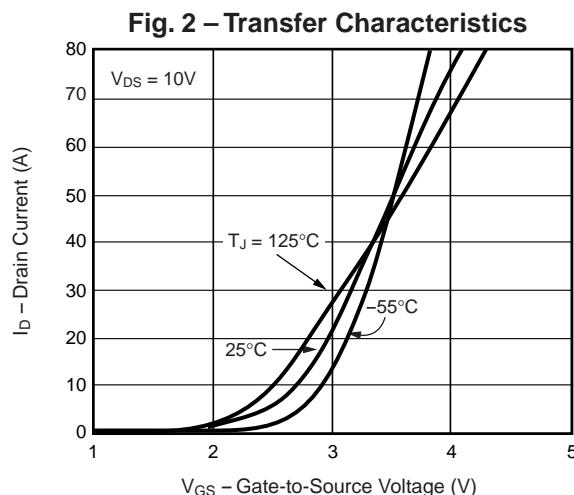
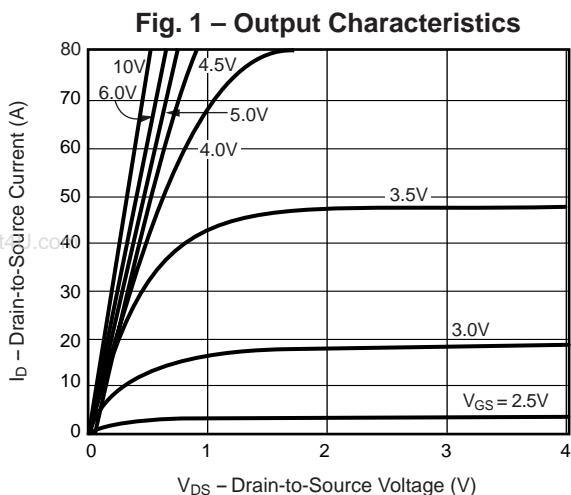
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 250\mu\text{A}$	30	—	—	V
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$	1.0	—	3.0	V
Gate-Body Leakage	I_{GSS}	$\text{V}_{\text{DS}} = 0\text{V}, \text{V}_{\text{GS}} = \pm 20\text{V}$	—	—	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}} = 30\text{V}, \text{V}_{\text{GS}} = 0\text{V}$	—	—	1.0	μA
On-State Drain Current ⁽¹⁾	$\text{I}_{\text{D(on)}}$	$\text{V}_{\text{DS}} \geq 5\text{V}, \text{V}_{\text{GS}} = 10\text{V}$	50	—	—	A
Drain-Source On-State Resistance ⁽¹⁾	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 15\text{A}$	—	6.2	7	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_D = 13\text{A}$	—	8.5	10	
Forward Transconductance ⁽¹⁾	g_{fs}	$\text{V}_{\text{DS}} = 15\text{V}, \text{I}_D = 15\text{A}$	—	50	—	S
Dynamic						
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=5\text{V}, \text{I}_D=15\text{A}$	—	31	43	nC
Gate-Source Charge	Q_{gs}	$\text{V}_{\text{DS}} = 15\text{V}, \text{V}_{\text{GS}} = 10\text{V}$ $\text{I}_D = 15\text{A}$	—	60	84	
Gate-Drain Charge	Q_{gd}		—	9	—	
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$		—	8.5	—	
Turn-On Rise Time	t_r	$\text{V}_{\text{DD}} = 15\text{V}, \text{R}_L = 15\Omega$ $\text{I}_D \approx 1\text{A}, \text{V}_{\text{GEN}} = 10\text{V}$ $\text{R}_G = 6\Omega$	—	13	26	ns
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		—	16	29	
Turn-Off Fall Time	t_f		—	94	132	
Input Capacitance	C_{iss}		—	38	57	
Output Capacitance	C_{oss}	$\text{V}_{\text{GS}} = 0\text{V}$ $\text{V}_{\text{DS}} = 15\text{V}$ $f = 1.0\text{MHz}$	—	3240	—	pF
Reverse Transfer Capacitance	C_{rss}		—	625	—	
			—	285	—	
Source-Drain Diode						
Max Diode Forward Current	I_s	—	—	—	20	A
Diode Forward Voltage ⁽¹⁾	V_{SD}	$\text{I}_s = 20\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	—	0.85	1.3	V

Notes: (1) Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$



N-Channel Enhancement-Mode MOSFET

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)



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Fig. 6 – On-Resistance vs. Gate-to-Source Voltage

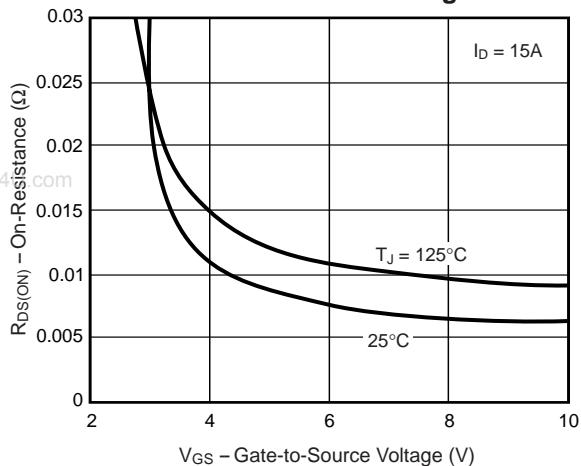


Fig. 7 – Gate Charge

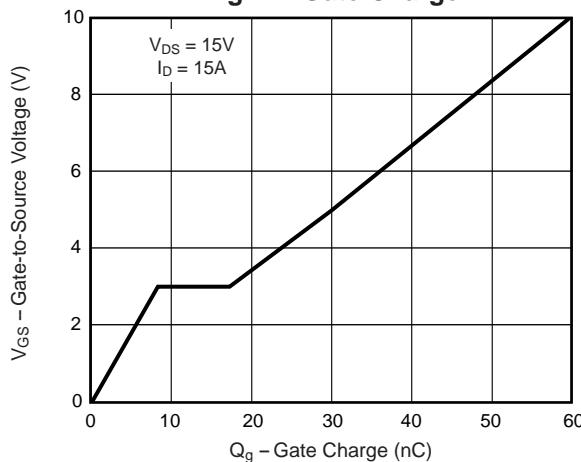


Fig. 8 – Capacitance

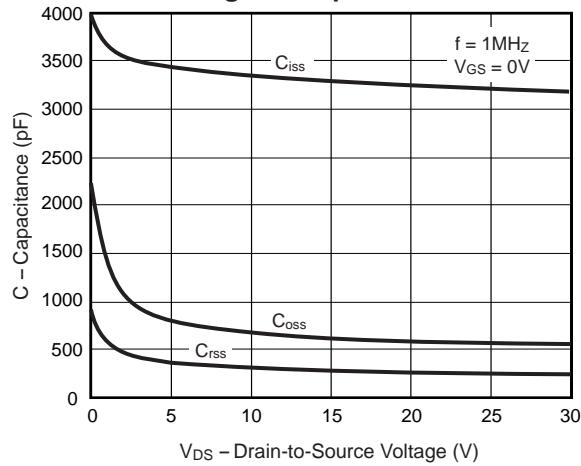
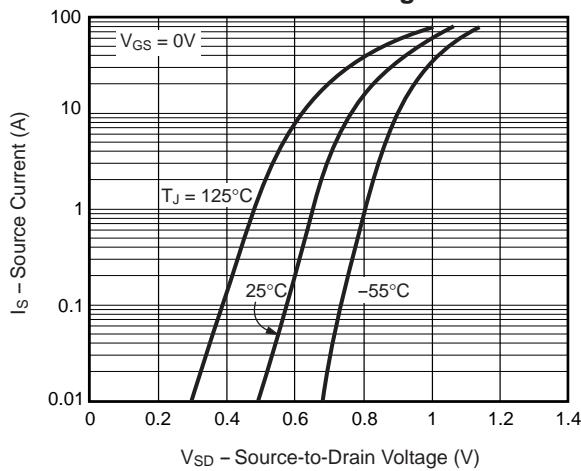


Fig. 9 – Source-Drain Diode Forward Voltage



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Fig. 10 – Breakdown Voltage vs. Junction Temperature

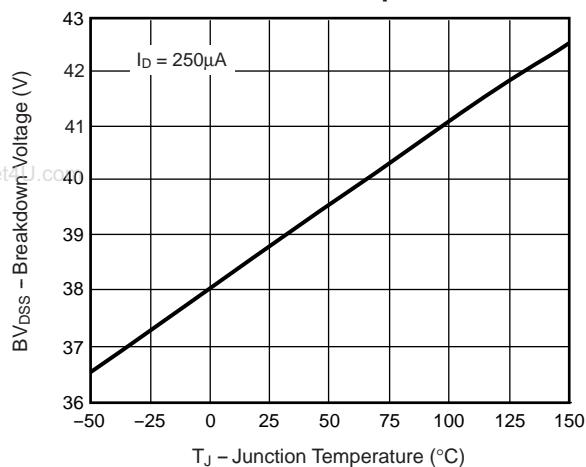


Fig. 11 – Transient Thermal Impedance

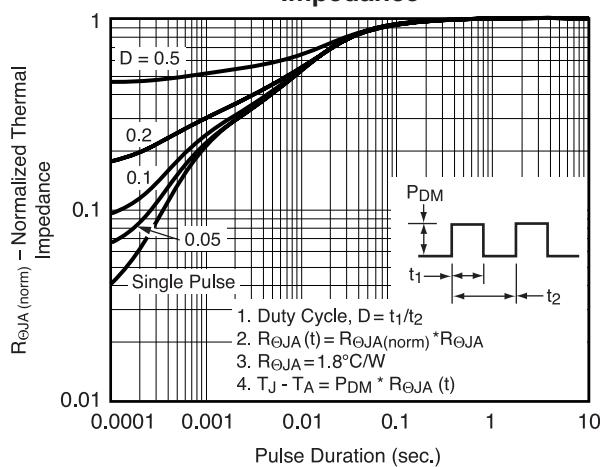


Fig. 12 – Power vs. Pulse Duration

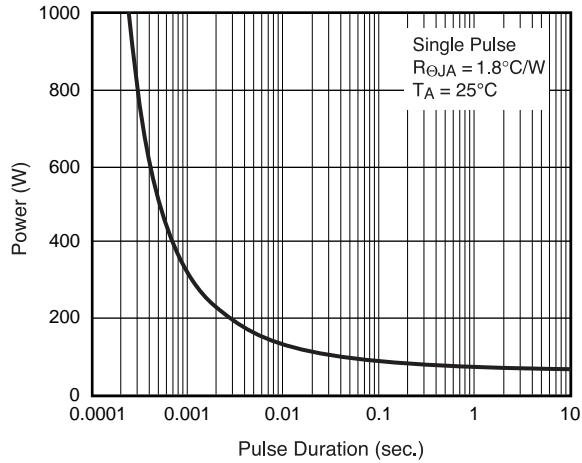


Fig. 13 – Maximum Safe Operating Area

